

Title (en)

DEVICE FOR CONNECTING MICROCOMPONENTS

Title (de)

EINRICHTUNG ZUR VERBINDUNG VON MIKROKOMPONENTEN

Title (fr)

DISPOSITIF POUR LA CONNEXION DE MICROCOMPOSANTS

Publication

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Application

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Abstract (en)

[origin: WO02064247A1] The invention relates to a device for connecting microcomponents (2), especially microreactors, which are preferably configured in the form of a plate and are preferably made of silicon. A sealing plate is arranged between the microcomponents (2). Said sealing plate is provided with openings (7) which correspond to openings (6) of the microcomponents (2).

IPC 1-7

**B01J 19/00; B01L 3/00**

IPC 8 full level

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Citation (search report)

See references of WO 02064247A1

Citation (examination)

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